

Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-719: Test methods for materials for interconnection structures - Relative permittivity and loss tangent (500 MHz to 10 GHz)

EESTI STANDARDI EESSÕNA

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See Eesti standard EVS-EN 61189-2-719:2016 sisaldab Euroopa standardi EN 61189-2-719:2016 ingliskeelset teksti.	This Estonian standard EVS-EN 61189-2-719:2016 consists of the English text of the European standard EN 61189-2-719:2016.
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English Version

Test methods for electrical materials, printed boards and other
interconnection structures and assemblies -
Part 2-719: Test methods for materials for interconnection
structures - Relative permittivity and loss tangent (500 MHz to 10
GHz)
(IEC 61189-2-719:2016)

Méthode d'essai pour les matériaux électriques, les cartes
imprimées et autres structures d'interconnexion et
ensembles - Partie 2-719: Méthodes d'essai des matériaux
pour structures d'interconnexion - Permittivité relative et
tangente de perte (500 MHz à 10 GHz)
(IEC 61189-2-719:2016)

Prüfverfahren für Elektromaterialien, Leiterplatten und
andere Verbindungsstrukturen und Baugruppen -
Teil 2-719: Prüfverfahren für Materialien von
Verbindungsstrukturen - Relative Permittivität und
Verlustfaktor (500 MHz bis 10 GHz)
(IEC 61189-2-719:2016)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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European foreword

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TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2-719: Test methods for materials for interconnection structures – Relative permittivity and loss tangent (500 MHz to 10 GHz)

1 Scope

This part of IEC 61189 specifies a test method of relative permittivity and loss tangent of printed board and assembly materials, expected to be determined 2 to 10 of relative permittivity and 0,001 to 0,050 of loss tangent at 500 MHz to 10 GHz.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

3 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60194 apply.

4 Test methods

4.1 Test specimens

4.1.1 General

The requirements with respect to test specimens are as follows.

- a) Specimens shall be copper clad laminate.
- b) Specimens shall be cut not less than 25 mm from the edge of the sheet.
- c) A minimum of four specimens shall be tested.

4.1.2 Size

The size of each specimen shall be $((200 \pm 0,5) \times (50 \pm 1))$ mm.

4.1.3 Thickness of dielectric

The dielectric thickness of each specimen shall be 0,6 mm to 1,6 mm. Typically 0,8 mm is suitable.

4.1.4 Thickness of copper foil

The copper foil thickness of each specimen should be 0,010 mm to 0,040 mm.